Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-70 (Canceled)

Claim 71 (Currently amended): A method of planarizing probes, wherein said probes are disposed to correspond to terminals of one or more devices to be tested and said probes are disposed on a plurality of substrates, said method comprising:

adjusting a shape of a surface of a first of said substrates without contacting said one or more devices to be tested, wherein a first plurality of said probes are attached directly to a first area of said surface of said first of said substrates and said adjusting a shape of a surface of a first of said substrates changes said shape of said surface of said first of said substrates at said first area and thereby changes a planar orientation of a contact portion of one of [[a]] said first plurality of said probes attached directly to said surface of said first substrate relative to another one of said first plurality of probes attached directly to said surface of said first substrate; and

adjusting a shape of a surface of a second of said substrates, wherein a second plurality of said probes [[is]] are attached directly to a second area of said surface of said second substrate and said adjusting a shape of a surface of a second of said substrates changes said shape of said surface of said second of said substrates at said second area and thereby changes a planar orientation of a contact portion of one of said second plurality of said probes attached directly to said surface of said second substrate relative to another one of said second plurality of probes attached directly to said surface of said second substrate.

Claim 72 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of said first substrate comprises selectively applying one of a push or a pull force to a first region of said first substrate.

Claim 73 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of said first substrate further comprises:

applying a pull force to a first region of said first substrate, and

applying a push force to a second region of said first substrate.

Claim 74 (Previously presented): The method of claim 73, wherein:

said first region corresponds to a central region of said surface of said first substrate,

said second region corresponds to a peripheral region of said surface of said first substrate.

Claim 75 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of said first substrate further comprises applying a plurality of forces to a plurality of regions of said first substrate.

Claim 76 (Canceled)

Claim 77 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of a second of said substrates comprises adjusting said shape without contacting said one or more devices to be tested.

Claim 78 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises activating an actuator configured to impart a selected one of a push force or a pull force to said first substrate.

Claim 79 (Previously presented): The method of claim 78, wherein said step of adjusting a shape of a surface of a second of said substrates comprises activating an actuator configured to impart a selected one of a push force or a pull force to said second substrate.

Claim 80 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises selectively activating a plurality of first actuators, each said first actuator configured to impart a push or a pull force to a different region of said first substrate.

Claim 81 (Previously presented): The method of claim 80, wherein at least one of said first actuators is configured to impart a selected one of a push or a pull force to said first substrate, and at least another of said first actuators is configured to impart only a push force to said first substrate.

Claim 82 (Previously presented): The method of claim 81, wherein said step of adjusting a shape of a surface of a second of said substrates comprises selectively adjusting a plurality of second actuators, each said second actuator configured to impart a push or a pull force to a different region of said second substrate.

Claim 83 (Previously presented): The method of claim 82, wherein at least one of said second actuators is configured to impart a selected one of a push or a pull force to said second substrate, and at least another of said second actuators is configured to impart only a push force to said second substrate.

Claim 84 (Previously presented): The method of claim 80, wherein said step of adjusting a shape of a surface of a second of said substrates comprises selectively activating a plurality of second actuators, each said second actuator configured to impart a push or a pull force to a different region of said second substrate.

Claim 85 (Previously presented): The method of claim 71, wherein said first plurality of probes comprises a first array of probes.

Claim 86 (Previously presented): The method of claim 85, wherein said second plurality of probes comprises a second array of probes.

Claim 87 (Previously presented): The method of claim 71, wherein each said probe of said first plurality of probes is elongate and resilient, whereby each said probe of said first plurality of probes provides individual compliance with respect to said terminals of said device to be tested and said step of adjusting a shape of said first of said substrates provides global planarization of said first plurality of probes with respect to said terminals of said device to be tested.

Claim 88 (Previously presented): The method of claim 87, wherein each said probe of said second plurality of probes is elongate and resilient, whereby each said probe of said second plurality of probes provides individual compliance with respect to said terminals of said device to be tested and said step of adjusting a shape of said second of said substrates provides global planarization of said second plurality of probes with respect to said terminals of said device to be tested.

Claims 89-101 (Canceled)

Claim 102 (Previously presented): The method of claim 78, wherein said first substrate comprises another surface opposite said surface to which said probes are attached, and said actuator applies said selected force directly to said another surface.

Claim 103 (Previously presented): The method of claim 78, wherein said actuator does not move said one or more devices to be tested.

Claim 104 (Previously presented): The method of claim 75, wherein said first substrate comprises another surface opposite said surface to which said probes are attached, and said plurality of regions are on said another surface.

Claim 105 (Previously presented): The method of claim 75, wherein said plurality of forces are not applied through said one or more devices to be tested.

Claim 106 (Previously presented): The method of claim 75, wherein said step of adjusting a shape of a surface of said first substrate comprises applying at least five forces to at least five regions of said first substrate.

Claim 107 (Previously presented): The method of claim 71, wherein said first of said substrates is disposed adjacent said second of said substrates such that said first plurality of said probes and said second plurality of said probes together form an array of probes disposed to contact said terminals of said one or more devices to be tested, and said step of adjusting a planarity of contact portions of said probes comprises planarizing said contact portions of said entire array of probes.

Claim 108 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises imparting a curvature to said surface.

Claim 109 (Previously presented): The method of claim 71, wherein said first substrate and said second substrate are part of a probe card assembly that further comprises a reference structure, wherein said step of adjusting a shape of a first substrate comprises adjusting said shape of said first substrate relative to said reference structure, and said step of adjusting a shape of a second substrate comprises adjusting said shape of said second substrate relative to said reference structure.

Claim 110 (Previously presented): The method of claim 71, wherein said shape of said surface of said first substrate and said shape of said surface of said second substrate are independently adjustable.

Claim 111 (Previously presented): The method of claim 71 further comprising adjusting said shape of said surface of said first substrate and adjusting said shape of said surface of said second substrate until an overall planar orientation of contact portions of said first plurality of probes and contact portions of said second plurality of probes change from a first planar relationship relative to one another to a second planar relationship relative to one another that is different than said first planar relationship.

Claim 112 (Previously presented): The method of claim 111, wherein said second planar relationship corresponds to a planar relationship of said terminals of said devices to be tested one with another.

Claim 113 (Canceled)

Claim 114 (Previously presented): The method of claim 80, wherein said first substrate and said second substrate are part of a probe card assembly that further comprises a reference structure.

Claim 115 (Currently amended): The method of claim 114, wherein said activating a plurality of actuators moves a plurality of said regions with respect to said reference structure, wherein at least one of said plurality of regions is moved toward said reference structure and at least one of said plurality of regions is moved away from said structure.

Claim 116 (Previously presented): The method of claim 114 further comprising:

activating a first of said actuators to apply a pull force to a first region of said first substrate, said pull force moving said first region of said first substrate toward said reference structure; and

activating a second of said actuators to apply a first push force to a second region of said first substrate, said first push force moving said second region of said first substrate away from said reference structure.

Claim 117 (Previously presented): The method of claim 116, wherein:

said first of said actuators comprises a first differential screw assembly, and said actuating said first of said actuators comprises rotating a first screw element of said first differential screw assembly; and

said second of said actuators comprises a second differential screw assembly, and said actuating said second of said actuators comprises rotating a second screw element of said second differential screw assembly.

Claim 118 (Previously presented): The method of claim 114, wherein each said actuator is configured to move a respective one of said different regions any distance in a range of distances toward or away from said reference structure.

Claim 119 (Previously presented): The method of claim 118, wherein each said actuator is configured to move said respective one of said different regions independent of said other actuators.

Claim 120 (Previously presented): The method of claim 80, wherein each said actuator is configured to apply said push or said pull force to a respective one of said regions of said first substrate independent of said other actuators.

Claim 121 (Currently amended): The method of claim 80, wherein each [[of]] said actuator is configured to apply a selectable level of said push or said pull force to a respective one of said regions of said first substrate independent of said other actuators.

Claim 122 (New): The method of claim 73, wherein said first substrate is monolithic, and said surface of said first substrate is a monolithic continuous surface.

Claim 123 (New): The method of claim 71, wherein said first surface of said first substrate is a monolithic continuous surface.